

**Surface Mount Glass Passivated
Bridge Rectifiers****Features**

- Glass passivated chip
- Ideal for automatic placement
- High surge forward current capability
- Reliable low cost construction utilizing molded plastic technique
- Lead tin plated copper
- Meet UL flammability classification 94V-0

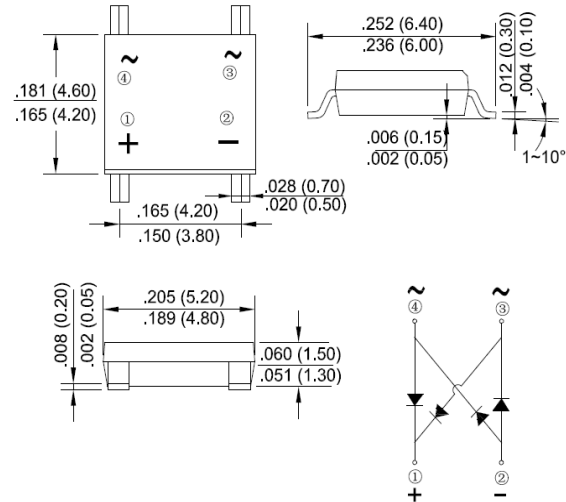
Mechanical Data

- Polarity: Symbol marked on body
- Mounting position: Any

Note: Products with logo  or  are made by HY Electronic (Cayman) Limited.

Applications

- General purpose use in AC/DC bridge full wave rectification, for SMPS, lighting ballaster, adapter, etc.

Reverse Voltage - 50 to 1000 Volts**Forward Current - 1.0 Amperes****ABS****RoHS
COMPLIANT**

Package Outline Dimensions in Inches (Millimeters)

Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Characteristics	Symbol	ABS105	ABS11	ABS12	ABS14	ABS16	ABS18	ABS110	Unit
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current @T _A =40 °C (Note1)	I _(AV)	1.0							A
Peak Forward Surge Current, 8.3mS Single Half Sine-Wave, Superimposed on Rated Load (JEDEC Method)	I _{FSM}	30							A
I ² t Rating for Fusing (t<8.3mS)	I ² t	3.7							A ² s
Peak Forward Voltage per Diode at 1.0A DC	V _F	1.05							V
Maximum DC Reverse Current at Rated @T _J =25°C	I _R	5							μA
DC Blocking Voltage per Diode @T _J =125°C		100							
Typical Thermal Resistance Junction to Ambient	R _{θJA}	80							°C/W
Operating Junction Temperature Range	T _J	-55 to +150							°C
Storage Temperature Range	T _{STG}	-55 to +150							°C

Notes: 1. Mounted on P.C. board.

2. The typical data above is for reference only.



Fig. 1 - Forward Current Derating Curve

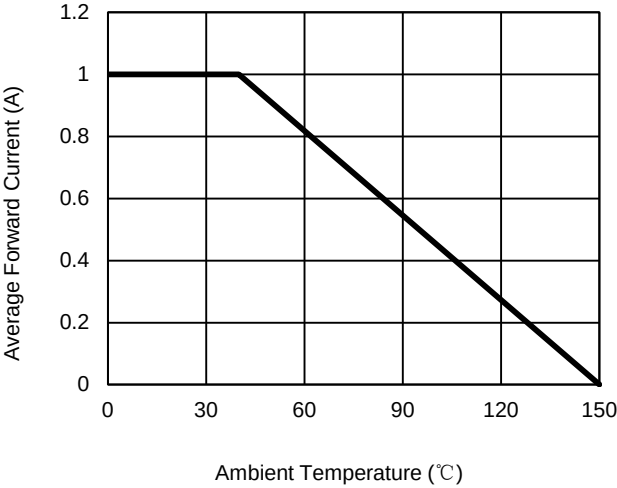


Fig. 2 - Maximum Non-Repetitive Surge Current

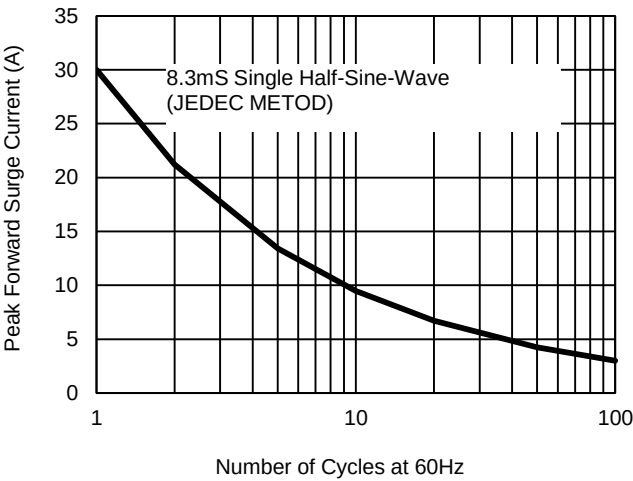


Fig. 3 - Typical Reverse Characteristics

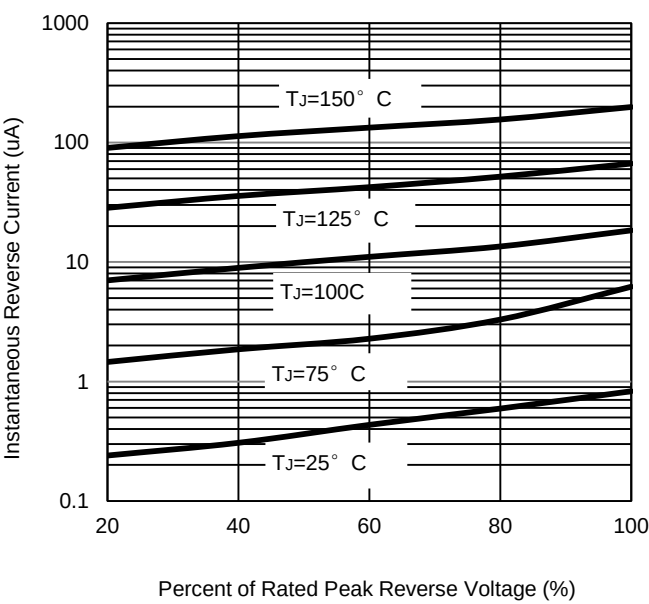
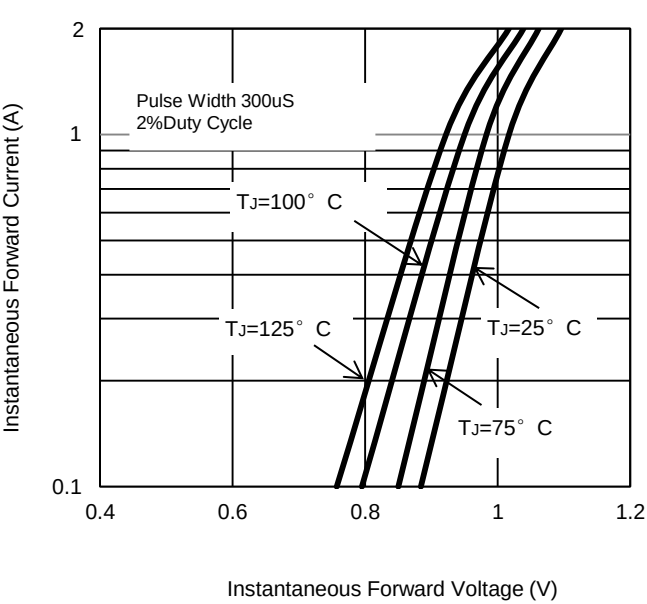


Fig. 4 - Typical Forward Characteristics





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